

Product Change Notification / CENO-20VJKH199

Date:

20-Mar-2023

Product Category:

Crypto Memory, Crypto RF

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5371 Initial Notice: Qualification of S703LS as an additional die attach material for selected AT88SCxx, AT88WJxx and AT88RF04C device families available in SCNC (12.6x12.6x0.58mm and 18.1x8.6x0.58mm) package.

Affected CPNs:

CENO-20VJKH199_Affected_CPN_03202023.pdf CENO-20VJKH199_Affected_CPN_03202023.csv

Notification Text:

PCN Status:Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of S703LS as an additional die attach material for selected AT88SCxx, AT88WJxx and AT88RF04C device families available in SCNC (12.6x12.6x0.58mm and 18.1x8.6x0.58mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	AIC Semiconductor Sdn Bhd	AIC Semiconductor Sdn Bhd	AIC Semiconductor Sdn Bhd			
-	(AIC)	(AIC)	(AIC)			
Wire Material	Au	Au	Au			
Die Attach Material	2035SC	2035SC	S703LS			
Molding Compound Material	Dam:DF698/Fill:4 670	Dam:DF698/Fill:467 0	Dam:DF698/Fill:4670			
Lead-Frame Material	Epoxy Glass Film base with Copper	Epoxy Glass Film base with Copper	Epoxy Glass Film base with Copper			

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve on time delivery performance by qualifying S703LS as an additional die attach material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: April 2023

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	March 2023				>	April 2023					
Workweek	9	1 0	1 1	1 2	1 3		1 4	1 5	1 6	1 7	1 8
Initial PCN Issue Date				х							
Qual Report Availability											х
Final PCN Issue											х

Date

Method to Identify Change: Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: March 20, 2023: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_CENO-20VJKH199 Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. CENO-20VJKH199 - CCB 5371 Initial Notice: Qualification of S703LS as an additional die attach material for selected AT88SCxx, AT88WJxx and AT88RF04C device families available in SCNC (12.6x12.6x0.58mm and 18.1x8.6x0.58mm) package.

Affected Catalog Part Numbers (CPN)

AT88SC0808CRF-MX1 AT88SC1616CRF-MX1 AT88SC3216CRF-MX1 AT88SC6416CRF-MX1 AT88SC0808CRF-MVA1 AT88SC6416CRF-MVA1 AT88RF04C-MX1G AT88WJ008-MX1G AT88WJ007-MVA1 AT88RF04C-MVA1